- Single Chip With Easy Interface Between UART and Serial-Port Connector of an External Modem or Other Computer Peripheral
- Five Drivers and Three Receivers Meet or Exceed the Requirements of TIA/EIA-232-F and ITU Recommendation V.28
- Designed to Support Data Rates up to 120 kbit/s
- ESD Protection Meets Or Exceeds 10 kV on RS-232 Pins and 5 kV on All Other Pins (Human-Body Model)
- Complement to the SN75185
- Pin-to-Pin Replacement for the Goldstar GD75323
- Functional Replacement for the MC145405

DW OR N PACKAGE (TOP VIEW) Vcc [20 🛮 V_{DD} 19 1DY 1DA **1** 2 2DA **∏** 3 18 2DY 3DA **∏** 4 17 1 3DY 1RY Π 5 16**∏** 1RA 2RY Γ 6 15 1 2RA 4DA **∏** 7 14 1 4DY 3RY **[**] 8 13**∏** 3RA 12 5DY 5DA [] 9 GND **1** 10 11 [] V_{SS}

description

The SN75196 combines five drivers and three receivers from the trade-standard SN75188 and SN75189 bipolar quadruple drivers and receivers, respectively. The flow-through design of the SN75196 decreases the part count, reduces the board space required, and allows easy interconnection of the UART and serial-port connector. The all-bipolar circuits and processing of the SN75196 provide a rugged, low-cost solution for this function.

The SN75196 complies with the requirements of TIA/EIA-232-F and ITU (formerly CCITT) V.28 standards. These standards are for data interchange between a host computer and peripheral at signal rates of up to 20 kbit/s. The switching speeds of the SN75196 are fast enough to support rates of up to 120 kbit/s with lower capacitive loads (shorter cables). Interoperability at the higher signaling rates cannot be assured unless the designer has design control of the cable and the interface circuits at both ends. For interoperability at signaling rates of up to 120 kbit/s, use of TIA/EIA-423-B (ITU V.10) and TIA/EIA-422-B (ITU V.11) standards are recommended.

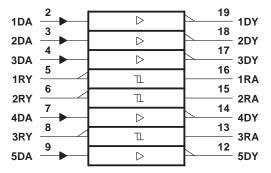
The SN75196 is characterized for operation over a temperature range of 0°C to 70°C.



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

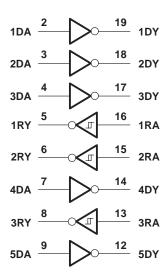


logic symbol†



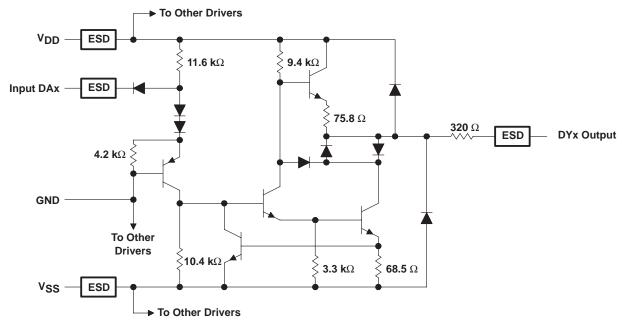
[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

logic diagram (positive logic)



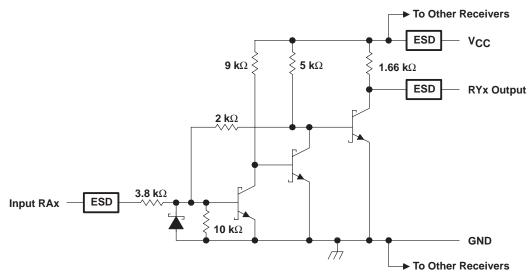


schematic of each driver



Resistor values shown are nominal.

schematic of each receiver



Resistor values shown are nominal.

absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V _{CC} (see Note 1)
Supply voltage, V _{DD} (see Note 1)
Supply voltage, V _{SS} (see Note 1)
Input voltage range, V _I : Driver
Receiver –30 V to 30 V
Output voltage range, V _O (Driver)
Low-level output current, I _{OL} (Receiver)
Continuous total power dissipation See Dissipation Rating Table
Electrostatic discharge: DY and RA to GND (see Note 2) Class 3, A: 10 kV, B: 500 V
All pins (see Note 2)
Storage temperature range, T _{stq} –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. All voltages are with respect to the network ground terminal.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25^{\circ}C$ POWER RATING	DERATING FACTOR‡ ABOVE T _A = 25°C	T _A = 70°C POWER RATING		
DW	1125 mW	9.0 mW/°C	720 mW		
N	1150 mW	9.2 mW/°C	736 mW		

[‡] This is the inverse of the traditional junction-to-case thermal resistance ($R_{\theta JA}$).

recommended operating conditions

		MIN	NOM	MAX	UNIT
Supply voltage, V _{DD}		7.5	9	13.5	V
Supply voltage, V _{SS}		-7.5	-9	-13.5	V
Supply voltage, V _{CC}		4.5	5	5.5	V
High-level input voltage, VIH	Driver	1.9			V
Low-level input voltage, V _{IL}	Driver			0.8	V
High level output ourrent leve	Driver			-6	mA
High-level output current, IOH	Receiver			-0.5	mA
High level output ourrent les	Driver			6	mA
High-level output current, IOL	Receiver			16	IIIA
Operating free-air temperature,TA	-	0		70	°C



^{2.} Per MIL-PRF-38535, Method 3015.7

supply currents over operating free-air temperature range

	PARAMETER		TEST CONDI	TIONS		MIN	MAX	UNIT
		All inputs at 1.9 V,	No load	$V_{DD} = 9 V$,	$V_{SS} = -9 V$		25	
	Supply current from VDD	All illputs at 1.9 v,	No load	$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$		32	mA
IDD	Зарріў сапені поні УДД	All inputs at 0.8 V,	No load	$V_{DD} = 9 V$,	$V_{SS} = -9 V$		7.5	IIIA
		All lilputs at 0.6 v,	No load	$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$		9.5	
		All inputs at 1.9 V,	No load	$V_{DD} = 9 V$,	$V_{SS} = -9 V$		-25	
	Supply current from VSS	All lilputs at 1.9 v,	No load	$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$		-32	mA
ISS	Supply current from VSS	All inputs at 0.8 V,	No load	$V_{DD} = 9 V$,	$V_{SS} = -9 V$		-5.3	IIIA
		All ilipuis at 0.6 v,	NO IOAU	$V_{DD} = 12 V$,	$V_{SS} = -12 \text{ V}$		-5.3	
ICC	Supply current from V _{CC}	V _{CC} = 5 V,	All inputs at 5 V,	No load			20	mA

DRIVER SECTION

electrical characteristics over operating free-air temperature range, $V_{DD} = 9 \text{ V}$, $V_{SS} = -9 \text{ V}$, $V_{CC} = 5 \text{ V}$, (unless otherwise noted)

	PARAMETER		TEST CONDIT	TIONS	MIN	TYP	MAX	UNIT
Vон	High-level output voltage	V _{IL} = 0.8 V,	$R_L = 3 k\Omega$,	See Figure 1	6	7.5		V
VOL	Low-level output voltage (see Note 3)	V _{IH} = 1.9 V,	$R_L = 3 k\Omega$,	See Figure 1		-7.5	-6	V
lн	High-level input current	V _I = 5 V,	See Figure 2				10	μΑ
I _{IL}	Low-level input current	$V_{I} = 0$,	See Figure 2				-1.6	mA
IOS(H)	High-level short-circuit output current (see Note 4)	V _{IL} = 0.8 V,	V _O = 0,	See Figure 1	-4.5	-9	-19.5	mA
IOS(L)	Low-level short-circuit output current (see Note 4)	V _{IH} = 2 V,	V _O = 0,	See Figure 1	4.5	9	19.5	mA
r _o	Output resistance (see Note 5)	V _{CC} = V _{DD} =	$= V_{SS} = 0,$	$V_0 = -2 \text{ V to } 2 \text{ V}$	300			Ω

- NOTES: 3. The algebraic convention, where the more positive (less negative) limit is designated as maximum, is used in this data sheet for logic levels only, e.g., if –10 V is a maximum, the typical value is a more negative voltage.
 - 4. Output short-circuit conditions must maintain the total power dissipation below absolute maximum ratings.
 - 5. Test conditions are those specified by TIA/EIA-232-F and as listed above.

switching characteristics, V_{DD} = 12 V, V_{SS} = -12 V, V_{CC} = 5 V $\pm 10\%$, T_A = 25°C

	PARAMETER		TEST CONDITION	ONS	MIN	TYP	MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	C _L = 15 pF,	See Figure 3		315	500	ns
tPHL	Propagation delay time, high- to low-level output	$R_L = 3 \text{ k}\Omega \text{ to } 7 \text{ k}\Omega,$	C _L = 15 pF,	See Figure 3		75	175	ns
	Transition time,	$R_1 = 3 k\Omega$ to $7 k\Omega$	$C_L = 15 pF$,	See Figure 3		60	100	ns
tTLH	low- to high-level output (see Note 6)	K[= 3 K22 tO 7 K22	$C_L = 2500 \text{ pF},$	See Figure 3 and Note 6		1.7	2.5	μs
t	Transition time, high- to low-level output	$R_1 = 3 k\Omega$ to $7 k\Omega$	$C_L = 15 pF$,	See Figure 3		40	75	ns
t _{THL}	(see Note 7)		C _L = 2500 pF,	See Figure 3 and Note 7	·	1.5	2.5	μs

NOTES: 6. Measured between –3-V and 3-V points of the output waveform (TIA/EIA-232-F conditions), all unused inputs are tied either high or low.

7. Measured between 3-V and –3-V points of the output waveform (TIA/EIA-232-F conditions), all unused inputs are tied either high or low.



RECEIVER SECTION

electrical characteristics over recommended operating conditions (unless otherwise noted)

	PARAMETER	ТІ	EST CONDITION	IS	MIN	TYP [†]	MAX	UNIT
\/	Positive-going input threshold voltage	See Figure 5	T _A = 25°C		1.75	1.9	2.3	V
VIT+	Positive-going input threshold voltage	See Figure 5	$T_A = 0^{\circ}C \text{ to } 70$	T _A = 0°C to 70 °C			2.3	٧
V _{IT} _	Negative-going input threshold voltage	See Figure 5			0.75	0.97	1.25	V
V _{hys}	Input hysteresis (V _{IT+} - V _{IT-})	See Figure 5			0.5			V
V	High-level output voltage	Jan - 0.5 m/	See Figure 5	V _{IH} = 0.75 V	2.6	4	5	V
VOH	nigii-level output voltage	$I_{OH} = -0.5 \text{ mA},$	See Figure 5	Inputs open	2.6			V
VOL	Low-level input voltage	$I_{OL} = 10 \text{ mA},$	V _I = 3 V,	See Figure 5		0.2	0.45	V
	High-level input current	V _I = 25 V			3.6		8.3	mA
ЧН	r ligh-lever input current	V _I = 3 V	V _I = 3 V					IIIA
1	Low-level input current	V _I = -25 V			-3.6		-8.3	mA
[†] 1∟	Low-level input current	$V_I = -3 V$						IIIA
los	Short-circuit output current	See Figure 4				-3.4	-12	mA

[†] All typical values are at $T_A = 25^{\circ}C$, $V_{CC} = 5$ V, $V_{DD} = 9$ V, and $V_{SS} = -9$ V.

switching characteristics, V_{CC} = 5 V, V_{DD} = 12 V, V_{SS} = -12 V, T_A = 25°C

	PARAMETER	TE	TEST CONDITIONS				MAX	UNIT
tPLH	Propagation delay time, low- to high-level output	$C_L = 50 \text{ pF},$	$R_L = 5 \text{ k}\Omega$,	See Figure 6		107	500	ns
tPHL	Propagation delay time, high- to low-level output	$C_L = 50 \text{ pF},$	$R_L = 5 \text{ k}\Omega$,	See Figure 6		42	150	ns
tTLH	Transition time, low- to high-level output	$C_L = 50 \text{ pF},$	$R_L = 5 \text{ k}\Omega$,	See Figure 6		175	525	ns
tTHL	Transition time, high- to low-level output	$C_L = 50 \text{ pF},$	$R_L = 5 \text{ k}\Omega$,	See Figure 6		16	60	ns



PARAMETER MEASUREMENT INFORMATION

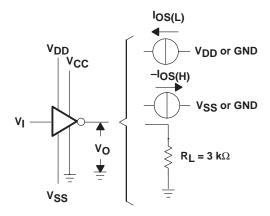


Figure 1. Driver Test Circuit for V_{OH} , V_{OL} , $I_{OS(H)}$, and $I_{OS(L)}$

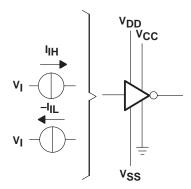
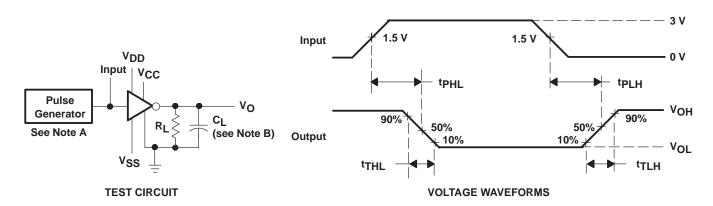


Figure 2. Driver Test Circuit for IIH and IIL



- NOTES: A. The pulse generator has the following characteristics: t_W = 25 μ s, PRR = 20 kHz, Z_O = 50 Ω , t_Γ = t_f < 50 ns.
 - B. C_L includes probe and jig capacitance.

Figure 3. Driver Test Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION

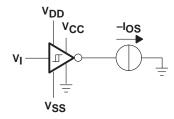


Figure 4. Receiver Test Circuit for IOS

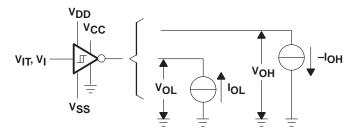
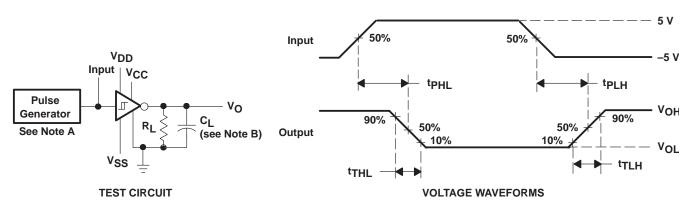


Figure 5. Receiver Test Circuit for V_{IT} , V_{OH} , and V_{OL}



NOTES: A. The pulse generator has the following characteristics: t_W = 25 μ s, PRR = 20 kHz, Z_O = 50 Ω , t_Γ = t_f < 50 ns.

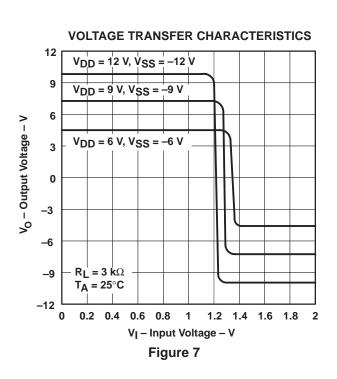
B. C_L includes probe and jig capacitance.

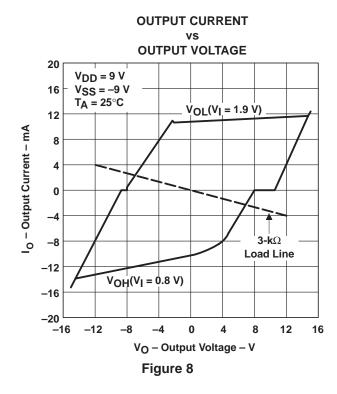
Figure 6. Receiver Propagation and Transition Times

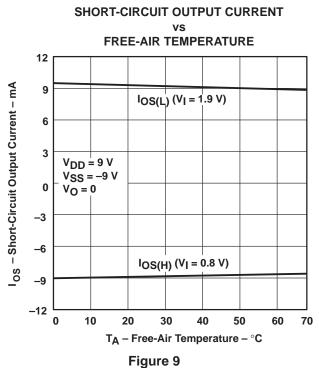


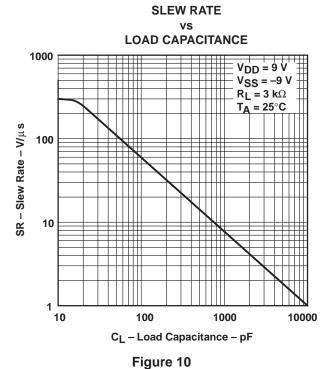
TYPICAL CHARACTERISTICS

DRIVER SECTION

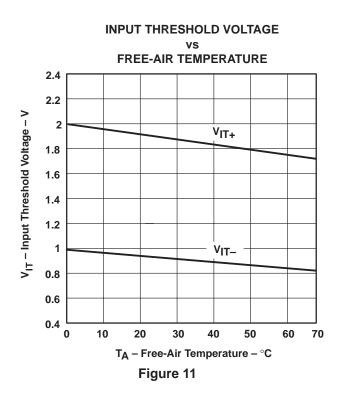


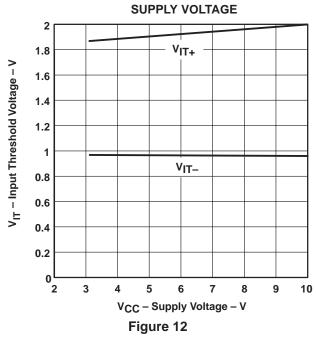




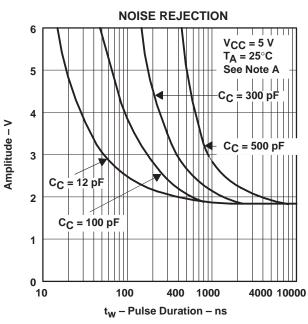


TYPICAL CHARACTERISTICS **RECEIVER SECTION**





INPUT THRESHOLD VOLTAGE



MAXIMUM SUPPLY VOLTAGE FREE-AIR TEMPERATURE 16 14 V_{DD} - Maximum Supply Voltage - V 12 10 8 6 4 2 $R_L \ge 3 \text{ k}\Omega$ (from each output to GND) 0 0 10 20 70 60 50 T_A – Free-Air Temperature – $^{\circ}C$

NOTE A: This figure shows the maximum amplitude of a positive-going pulse that, starting from 0 V, does not cause a change of the output level.

Figure 14





APPLICATION INFORMATION

Diodes placed in series with the V_{DD} and V_{SS} terminals protect the SN75196 in the fault condition when the device outputs are shorted to V_{DD} or V_{SS} and the power supplies are at low and provide low-impedance paths to ground (see Figure 15).

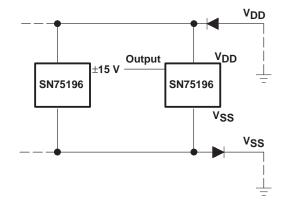
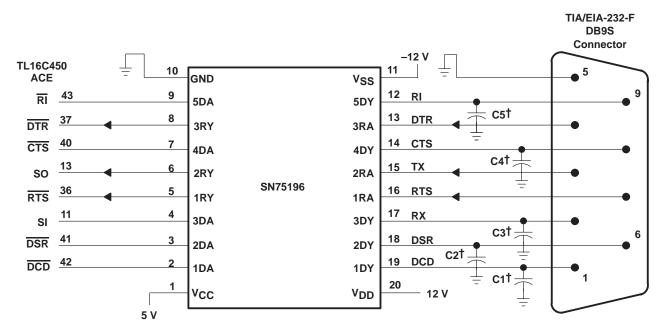


Figure 15. Power-Supply Protection to Meet Power-Off Fault Conditions of TIA/EIA-232-F



[†] See Figure 10 to select the correct values for the loading capacitors (C1, C2, C3, C4, and C5), which may be required to meet the RS-232 maximum slew-rate requirement of 30 V/μs. The value of the loading capacitors required depends upon the line length and desired slew rate, but is typically 330 pF.

NOTE A: To use the receivers only, $V_{\mbox{DD}}$ and $V_{\mbox{SS}}$ must both be powered or tied to ground.

Figure 16. Typical TIA/EIA-232-F Connection

www.ti.com 11-Nov-2025

PACKAGING INFORMATION

Orderable part number	Status	Material type	Package Pins	Package qty Carrier	RoHS	Lead finish/	MSL rating/	Op temp (°C)	Part marking
	(1)	(2)			(3)	Ball material	Peak reflow		(6)
						(4)	(5)		
SN75196DW	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75196
SN75196DW.A	Active	Production	SOIC (DW) 20	25 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75196
SN75196DWR	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75196
SN75196DWR.A	Active	Production	SOIC (DW) 20	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	0 to 70	SN75196

⁽¹⁾ Status: For more details on status, see our product life cycle.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

⁽²⁾ Material type: When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ RoHS values: Yes, No, RoHS Exempt. See the TI RoHS Statement for additional information and value definition.

⁽⁴⁾ Lead finish/Ball material: Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ MSL rating/Peak reflow: The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

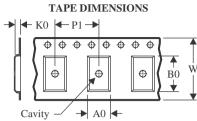
⁽⁶⁾ Part marking: There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

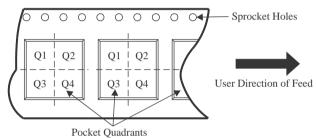
TAPE AND REEL INFORMATION





A0	Dimension designed to accommodate the component width
В0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

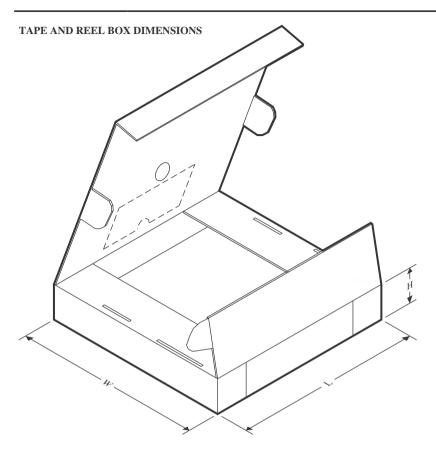


*All dimensions are nominal

Device		Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75196DWR	SOIC	DW	20	2000	330.0	24.4	10.8	13.3	2.7	12.0	24.0	Q1

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025



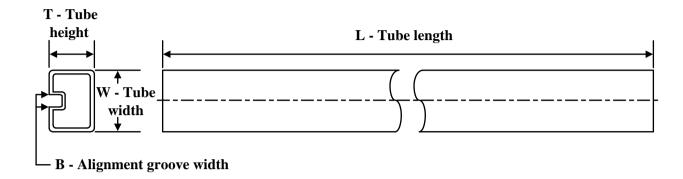
*All dimensions are nominal

Ì	Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)	
ı	SN75196DWR	SOIC	DW	20	2000	356.0	356.0	45.0	

PACKAGE MATERIALS INFORMATION

www.ti.com 24-Jul-2025

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (µm)	B (mm)
SN75196DW	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75196DW	DW	SOIC	20	25	507	12.83	5080	6.6
SN75196DW.A	DW	SOIC	20	25	506.98	12.7	4826	6.6
SN75196DW.A	DW	SOIC	20	25	507	12.83	5080	6.6



SOIC



NOTES:

- 1. All linear dimensions are in millimeters. Dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.

 2. This drawing is subject to change without notice.

 3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not
- exceed 0.15 mm per side.
- 4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.43 mm per side.
- 5. Reference JEDEC registration MS-013.



SOIC



NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.



SOIC



NOTES: (continued)

- 8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
- 9. Board assembly site may have different recommendations for stencil design.



IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale, TI's General Quality Guidelines, or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2025, Texas Instruments Incorporated

Last updated 10/2025